

A

B

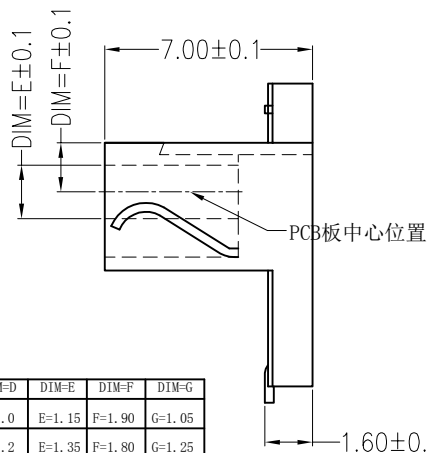
C

D

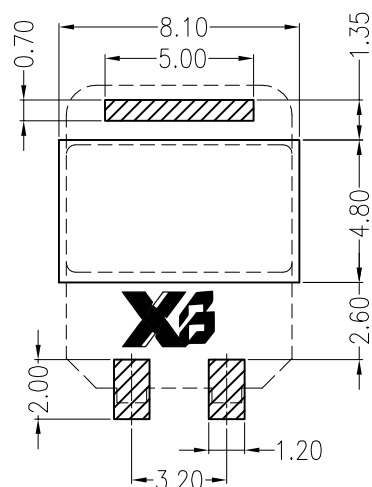
E

F

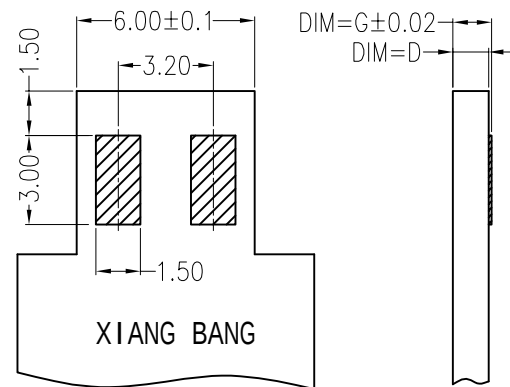
REV	DESCRIPTION	DESIGN	DATE
A0	Release	吴丹平	2017.03.23



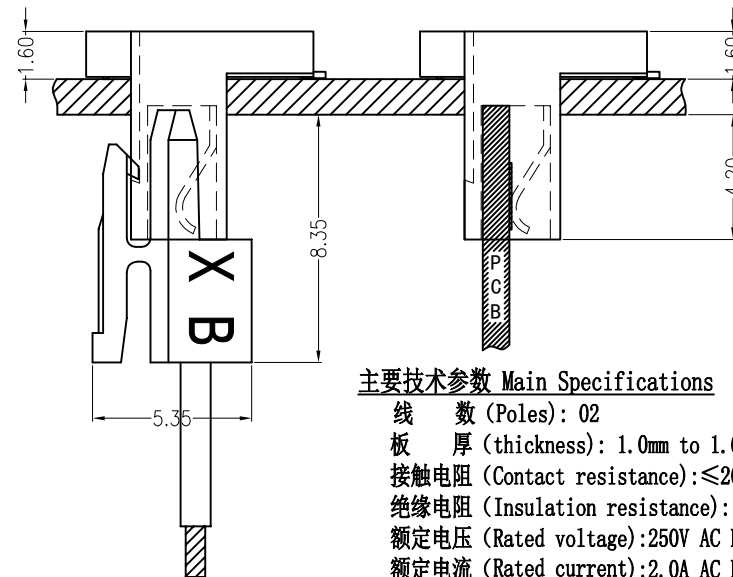
PCB板厚	DIM=D	DIM=E	DIM=F	DIM=G
PCB=1.0	D=1.0	E=1.15	F=1.90	G=1.05
PCB=1.2	D=1.2	E=1.35	F=1.80	G=1.25
PCB=1.6	D=1.6	E=1.75	F=1.60	G=1.65



Board Layout



Mating PCB detail



主要技术参数 Main Specifications

线 数 (Poles): 02
板 厚 (thickness): 1.0mm to 1.6mm
接触电阻 (Contact resistance): $\leq 20m\Omega$
绝缘电阻 (Insulation resistance): $\geq 1000M\Omega$
额定电压 (Rated voltage): 250V AC DC
额定电流 (Rated current): 2.0A AC DC
耐 电 压 (Withstand Voltage): 1000V AC/minute
温度范围 (Temperature Range): $-25^{\circ}C \sim +105^{\circ}C$

ORDER INFORMATION:

XB-L002-**-F2MB-R			
PART No.			PACKAGING:
No. FOR PCB:			R=REEL
1.0mm/1.2mm/1.6mm			P=PE
PLASTIC MATERIAL:			PLATING:
F2M=LCP (BEIGE)			B=MATTE Sn

C	SOLDER TAB	2 PCS	PhosphorBronze	MATTE Sn-plated
B	CONTACT	2 PCS	PhosphorBronze	MATTE Sn-plated
A	PEDESTAL	1 PCS	LCP	UL 94V-0, COLOR:BEIGE
ITEM	COMPONENT	Q'TY	MATERIAL	FINISH
东莞市溪榜电子有限公司				
TITLE: -				
3.2mmPITCH 180°WAFER SMT TYPE				
X.±0.5	X.±5°	USE:	PART NO.:	
.X±0.3	.X±2°	CUSTOMER	L002-**-F2MB-R	
.XX±0.25	.XX±1°	APPD:	DWG NO.:	
--	--	邵敬和	GCCP-0003	
⊕	⊖	CHKD:	SCALE	
UNITS: mm	DR:	田 峰	1 : 1	
		吴丹平	SHEET	
			1 / 1	